

## **IN THE CLAIMS:**

### **Amendments to the Claims**

Please amend claim 33 and 42 as shown below, and please cancel claim 34 without prejudice or disclaimer of the subject matter thereof.

### **Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-32 (canceled)

33. (currently amended) A semiconductor laser module comprising:  
a semiconductor laser;  
a driving circuit for driving said semiconductor laser; and  
a temperature control means for controlling the temperature of the semiconductor laser;

wherein said temperature control means includes a heating element without a cooling element for controlling temperature of said semiconductor laser, a temperature sensor for sensing ~~ambient air~~ temperature of said semiconductor laser, and a temperature module for controlling said heating element on the basis of temperature information from said temperature sensor so as to maintain said semiconductor laser ~~at least at a temperature of the~~ which is higher than ambient air temperature of said semiconductor laser.

Claim 34 (canceled)

35. (previously presented) A semiconductor laser module according to claim 34, wherein said semiconductor laser is mounted on said heating element through an insulating film for electrically separating the heat element from said semiconductor laser so as to be thermally combined, and a laminated thin film is provided for joining said semiconductor laser to said insulating film.

36. (previously presented) A semiconductor laser module according to claim 34, wherein said semiconductor laser and said heating element are molded into a plastic module, and the ambient temperature is air temperature outside of said module.

37. (previously presented) A semiconductor laser module according to claim 34, further comprising a supporting substrate, said semiconductor laser, said heating element and said temperature sensor being mounted on said supporting substrate, wherein said heating element controls a temperature of said supporting substrate together with said semiconductor laser.

38. (previously presented) A semiconductor laser module according to claim 34, wherein said semiconductor laser is a Fabry-Perot type laser.

39. (previously presented) A semiconductor laser according to claim 34, wherein said semiconductor laser is a modulator integrated laser.

40. (previously presented) A semiconductor laser module according to claim 37, wherein said semiconductor laser, said heating element and said temperature sensor are mounted on a main surface of said supporting substrate, wherein a main surface of a semiconductor chip of said semiconductor laser, on

which a joining for emitting laser light has been formed, is disposed on said main surface of said supporting substrate, and wherein said heating element is disposed in proximity to said joining on said main surface of said semiconductor chip of said semiconductor laser on said main of said supporting substrate.

41. (previously presented) A semiconductor laser module according to claim 39, wherein said heating element is disposed between a main surface of a semiconductor chip of said semiconductor laser and a main surface of said supporting substrate.

42. (currently amended) A semiconductor laser module according to claim 33, wherein said semiconductor laser is maintained ~~at least at~~ the temperature of which is higher than the ambient air temperature of said semiconductor laser only by controlling said heating element.